

标准&定制开关连接器产品制造商

DONG GUAN XI BANG ELECTRONICS CO., LTD.

规 格 书 SPECIFICATION

CUSTOMER NAM	客户名称:	
CUSTOMER NO.	客户编号:	
SERIES	系列	CSD系列存储卡插槽
MODEL NO.	型 号:	XB-series
DRAWING NO.	图形号	CSD Series Memory Card Sockets

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求,敬请确认此规格书内所有项目 并签名和盖章后回传给我司,以作我司产品制作之

依据和存档之用,多谢合作!

EXAMINE & APPROVAL 审批

APPROVE 接受			NOT APPROVE 不接受
SIGNATURE 签署	STAMP盖章	DATE日期	

PREPARED BY.制表人	CHECKED BY.校对	APPROVED BY.审核	APPROVAL BY. 批准
研发部	品质部	工程部	总经办
戴海明	黄自清	庞军	吴量
2022, 06, 08	2022, 06, 08	2022, 06, 08	2022, 06, 08

东莞市溪榜电子有限公司

Dong guan Xi Bang Electronics Co., Ltd

地址:广东省东莞市黄江镇合路工业区

Address: He Lu Industrial Zone, Huangjiang Town

,Dongguan City, Guangdong Province

Tel: (0769)82055138/82056828

Fax:(0769)83663452

邮箱: admin@alspr.com switch@alspr.com http://www.alpsr.com/ http://www.alpsr.com/

Dong Guan XB ElectronicsCo., Ltd

AccountNumber: 705540238

BankName: CitibankN.A., HongKongBranch

Country/Region:Hong Kong

BankCode:006

BankAddress: 3GardenRoad, Central, Hong Kong

SWIFT/BIC: CITIHKHX(CITIHKHXXXX*If11charactersare

required)

MAIL: HK@ALPSR. CN XB@ALPSR. CN XB@ALPSR. COM

Quality core! Afterburner for Made in China!

ENGINEERING PRODUCT SPECIFICATION SPEC.NO.: SPCSD12A

DEPT. For Secure Digital Connector PAGE: 1/3

1. SCOPE:

This specification covers performance, tests and quality requirements for SD Card Connector

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

MIL - STD - 1344 Test methods for electrical connectors

3. PART NO.: CSD-09A001Z / CSD-09A001Z-R0-LF

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

A. Contact: Copper alloy

B. Housing: Hi-temp. plastic UL94-V0

C. WP Contact: Copper alloy

D. Shell: Stainless picking

6. ACCOMMOATED P.C.BOARD

See attached drawings

REVIEWED : XIE. BING. XIN APPROVED : HE. LONG. FEI VERIFIED : PANG. DONG .

ENGINEERING	PRODUCT SPECIFICATION	SPEC.NO.:	SPCSD12A
DEPT.	For Secure Digital Connector	PAGE:	2/3

7. ELECTRICAL PERFORMANCE:

	ITEN	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		0.5A 5V AC max.
7.2	Contact Resistance	Measured between plug solder tails and receptacle solder tails. (EIA364-23)	60 mΩ Max.
7.3	Dielectric strength	Test between center contact and outer shell for one minute. 500V AC(r.m.s) (EIA364-20)	No Breakdown
7.4	Insulation Resistance	Test between center contact and outer shell of unmated samples for one minute. at 500V DC (EIA364-21)	1000MΩ Min.

8. MECHANICAL PERFORMANCE:

	ITEN	TEST CONDITION	REQUIREMENT
8.1	Mating Force	Measure force necessary to mate printed circuit board to samples using free floating fixtures at maximum rate of .5 inch per minute	2.0kg Max
8.2	Un-mating Force	Measure force necessary to un-mate printed circuit board from samples at maximum rate of .5 inch per minute	2.0kg Max 0.1kg Min
8.3	Durability	Mate connectors up to 10000 cycles at a maximum rate of 400 to 600 cycles per hour prior to environmental test	No abnormality After test contact resistance shell not exceed $100 \text{m}\Omega$ max.

9. ENVIRONMENTAL PERFORMANCE:

	ITEN	TEST CONDITION	REQUIREMENT
9.1	Humidity	There shall be no any excessive corrosion on the every part of connector. Temperature: 40±2°C Humidity: 90~95%RH Test time: 96hours (EIA364-31A)	No abnormality After test contact resistance shell not exceed $100 \text{m}\Omega$ max.
9.2	High Temperature Life	Temperature: 85±2°C Test time: 96hours (EIA364-31A)	No abnormality After test contact resistance shell not exceed $100 \text{m}\Omega$ max.

ENGINEERINGPRODUCT SPECIFICATIONSPEC.NO.:SPCSD12ADEPT.For Secure Digital ConnectorPAGE:3/3

	ITEN	TEST CONDITION	REQUIREMENT
9.3	Cold resistance	Temperature: -25±2°C Test time: 96hours (EIA364-31A)	No abnormality After test contact resistance shell not exceed 100mΩ max.
9.4	Solder ability	Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5 ° C	Minimum: 95% of immersed area
9.5	Soldering Heat Resistance	SMT Type Lead-Free Process: Soldering time: 10 sec Max. Soldering pot.: 260°C Max. Refer Reflow temperature profile(11.1)	No damage
9.6	Vibration	During vibration, there shall be no discontinuity of the circuit greater then 1 microsecond or longer duration: 15minutes / axis (EIA364-28B, test condition I)	No abnormality After test contact resistance shell not exceed $100 \text{m}\Omega$ max.

10. OPERATING TEMPERATURE RANGE: -25° ~ °C

- 11. Recommended IR Reflow Temperature Profile:
 - 11.1 Using Lead-Free Solder Paste

Temperature

